



# 74LVTN16374

## 3.3V, 16-Bit D-Type Edge-Triggered Flip-Flop with 3-State Outputs

---

### GENERAL DESCRIPTION

The 74LVTN16374 is 16-bit D-type edge-triggered flip-flop with non-inverting 3-state outputs which is designed 3.3V supply voltage. The device can provide capability in driving highly capacitive or relatively low-impedance loads. That makes it especially suitable for use in implementing buffer registers, I/O ports, bidirectional bus drivers and working registers.

The device is capable of using as two 8-bit flip-flops or one 16-bit flip-flop. For flip-flop, when the clock input nCP is on the positive transition, the nQn outputs will follow logic levels of the nDn inputs.

An output enable ( $\overline{nOE}$ ) input can make the eight outputs set to either high/low logic levels or high-impedance state.

$\overline{nOE}$  has no effect on built-in function of the flip-flop. When all outputs are in the high-impedance state, old data can be reserved or new data can be entered.

### FEATURES

- **Wide Operating Voltage Range: 3.3V**
- **Input and Output Interface Capability to 5V System Environment**
- **+64mA/-32mA Output Current**
- **16-Bit Edge-Triggered Flip-Flop**
- **3-State Buffers**
- **Input and Output Switching Levels of TTL**
- **Power-up Reset**
- **Power-up 3-State**
- **No Bus Current Loading when Output is Connected to 5V Bus**
- **-40°C to +125°C Operating Temperature Range**
- **Available in a Green TSSOP-48 Package**

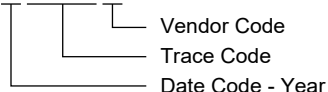
## PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
74LVTN16374	TSSOP-48	-40°C to +125°C	74LVTN16374XTS48G/TR	74LVTN16374 XTS48 XXXXX	Tape and Reel, 2500

## MARKING INFORMATION

NOTE: XXXXX = Date Code, Trace Code and Vendor Code.

**XXXXX**



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS <sup>(1)</sup>

Supply Voltage, $V_{CC}$ .....	-0.5V to 4.6V
Input Voltage, $V_I$ <sup>(2)</sup> .....	-0.5V to 7V
Output Voltage, $V_O$ <sup>(2)</sup> .....	
High-Impedance State .....	-0.5V to 7V
High-State or Low-State.....	-0.5V to MIN (7V, $V_{CC} + 0.5V$ )
Input Clamping Current, $I_{IK}$ ( $V_I < 0V$ ).....	-50mA
Output Clamping Current, $I_{OK}$ ( $V_O < 0V$ ).....	-50mA
Output Current, $I_O$	
High-State .....	-64mA
Low-State .....	128mA
Supply Current, $I_{CC}$ .....	128mA
Ground Current, $I_{GND}$ .....	-256mA
Junction Temperature <sup>(3)</sup> .....	+150°C
Storage Temperature Range .....	-65°C to +150°C
Lead Temperature (Soldering, 10s).....	+260°C
ESD Susceptibility	
HBM.....	7000V
CDM .....	1000V

## RECOMMENDED OPERATING CONDITIONS

Supply Voltage, $V_{CC}$ .....	2.7V to 3.6V
Input Voltage, $V_I$ .....	0V to 5.5V
Output Voltage, $V_O$	
High-Impedance State .....	0V to 5.5V
High-State or Low-State.....	0V to $V_{CC}$
High-Level Output Current, $I_{OH}$ .....	-32mA
Low-Level Output Current, $I_{OL}$ .....	64mA
Input Transition Rise and Fall Rate, $\Delta t/\Delta V$	
.....	10ns/V (MAX)
Operating Temperature Range .....	-40°C to +125°C

## OVERSTRESS CAUTION

1. Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.
2. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.
3. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.

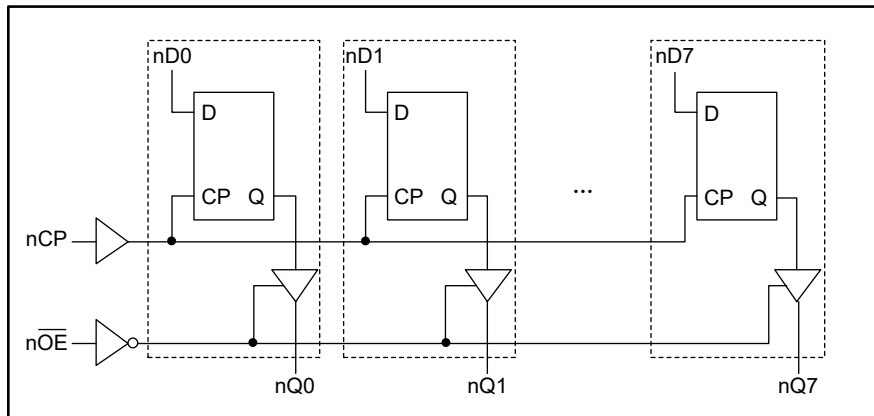
## ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

## DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

## LOGIC DIAGRAM



## FUNCTION TABLE

OPERATING MODE	CONTROL INPUT			INTERNAL REGISTER	OUTPUT
	nOE	nCP	nDn		nQn
Load and Read Register	L	↑	l	L	L
	L	↑	h	H	H
Hold	L	NC	X	NC	NC
Disable Outputs	H	NC	X	NC	Z
	H	↑	nDn	nDn	Z

H = High Voltage Level

L = Low Voltage Level

↑ = Low-to-High Clock Transition

h = High Voltage Level One Set-Up Time Prior to the Low-to-High Clock Transition

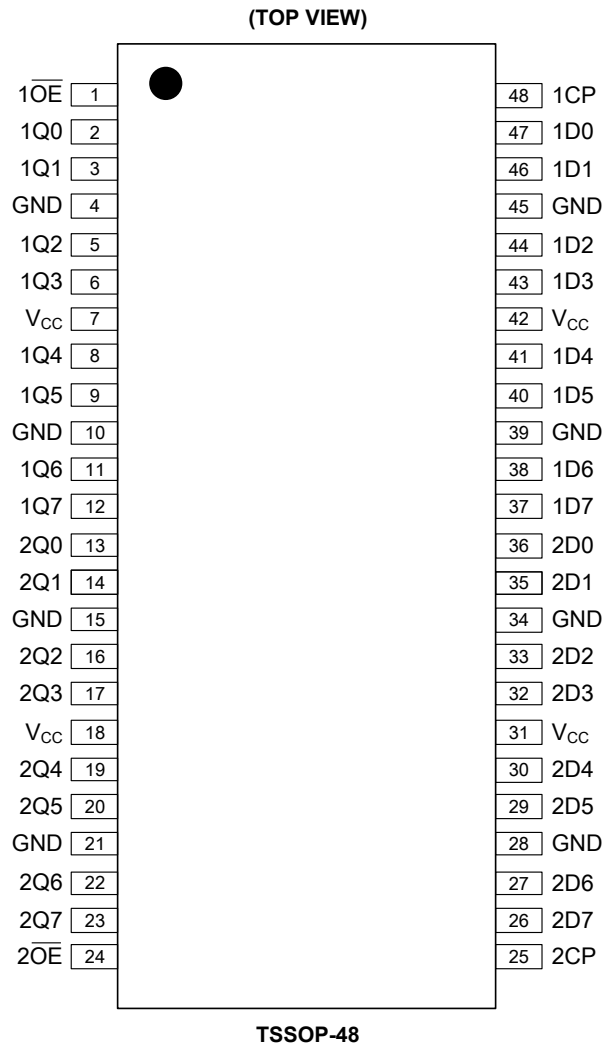
l = Low Voltage Level One Set-Up Time Prior to Low-to-High Clock Transition

Z = High-Impedance State

NC = No Change

X = Don't Care

## PIN CONFIGURATION



## PIN DESCRIPTION

PIN	NAME	FUNCTION
47, 46, 44, 43, 41, 40, 38, 37	1D0, 1D1, 1D2, 1D3, 1D4, 1D5, 1D6, 1D7	Data Inputs.
36, 35, 33, 32, 30, 29, 27, 26	2D0, 2D1, 2D2, 2D3, 2D4, 2D5, 2D6, 2D7	Data Inputs.
1, 24	1OE, 2OE	Output Enable Inputs (Active Low).
48, 25	1CP, 2CP	Clock Inputs.
2, 3, 5, 6, 8, 9, 11, 12	1Q0, 1Q1, 1Q2, 1Q3, 1Q4, 1Q5, 1Q6, 1Q7	Data Outputs.
13, 14, 16, 17, 19, 20, 22, 23	2Q0, 2Q1, 2Q2, 2Q3, 2Q4, 2Q5, 2Q6, 2Q7	Data Outputs.
4, 10, 15, 21, 28, 34, 39, 45	GND	Ground.
7, 18, 31, 42	V <sub>CC</sub>	Supply Voltage.

## ELECTRICAL CHARACTERISTICS

(Full = -40°C to +125°C, all typical values are measured at  $V_{CC} = 3.3V$  and  $T_A = +25^\circ C$ , unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS	
Input Clamping Voltage	$V_{IK}$	$V_{CC} = 2.7V, I_{IK} = -18mA$	Full	-1.2	-0.78		V	
High-Level Input Voltage	$V_{IH}$	$V_{CC} = 2.7V$ to 3.6V	Full	2			V	
Low-Level Input Voltage	$V_{IL}$	$V_{CC} = 2.7V$ to 3.6V	Full			0.8	V	
High-Level Output Voltage	$V_{OH}$	$I_{OH} = -100\mu A, V_{CC} = 2.7V$ to 3.6V	Full	$V_{CC} - 0.05$	$V_{CC} - 0.001$		V	
		$I_{OH} = -8mA, V_{CC} = 2.7V$	Full	2.45	2.6			
		$I_{OH} = -32mA, V_{CC} = 3.0V$	Full	2.1	2.65			
Low-Level Output Voltage	$V_{OL}$	$V_{CC} = 2.7V$	$I_{OL} = 100\mu A$	Full		0.001	0.05	V
			$I_{OL} = 24mA$	Full		0.15	0.28	
		$V_{CC} = 3.0V$	$I_{OL} = 16mA$	Full		0.1	0.18	
			$I_{OL} = 32mA$	Full		0.2	0.36	
			$I_{OL} = 64mA$	Full		0.4	0.55	
Power-Up Low-Level Output Voltage <sup>(1)</sup>	$V_{OL\_PU}$	$V_{CC} = 3.6V, I_{OL} = 1mA, V_I = V_{CC}$ or GND	Full		5	50	mV	
Input Leakage Current	$I_I$	Control pins, $V_{CC} = 3.6V, V_I = V_{CC}$ or GND	Full		$\pm 0.01$	$\pm 1$	$\mu A$	
		Control pins, $V_{CC} = 0V$ or 3.6V, $V_I = 5.5V$	Full		0.01	5		
		Input data pins <sup>(2)</sup> , $V_{CC} = 0V$ or 3.6V, $V_I = 5.5V$	Full		0.01	5		
		Input data pins <sup>(2)</sup> , $V_{CC} = 3.6V, V_I = V_{CC}$	Full		0.01	1		
		Input data pins <sup>(2)</sup> , $V_{CC} = 3.6V, V_I = GND$	Full	-2	-0.01			
Off-State Output Current	$I_{OZ}$	$V_{CC} = 3.6V$	$V_O = 3.0V$	Full		0.01	2	$\mu A$
			$V_O = 0.5V$	Full	-2	-0.01		
Output Leakage Current	$I_{LO}$	Output in high-state when $V_O > V_{CC}$ , $V_O = 5.5V, V_{CC} = 3.0V$	Full		1	30	$\mu A$	
Power-Up/Down Output Current	$I_{O\_PU/PD}$	$V_{CC} \leq 1.2V, V_O = 0.5V$ to $V_{CC}, V_I = GND$ or $V_{CC}$ , $nOE = \text{don't care}$	+25°C		0.01	10	$\mu A$	
Power-Off Leakage Current	$I_{OFF}$	$V_{CC} = 0V, V_I$ or $V_O = 0V$ to 5.5V	Full		0.01	10	$\mu A$	
Supply Current	$I_{CC}$	$V_{CC} = 3.6V,$ $V_I = GND$ or $V_{CC},$ $I_O = 0A$	Outputs high	Full		12	80	$\mu A$
			Outputs low	Full		12	80	
			Outputs disabled <sup>(3)</sup>	Full		12	80	
Additional Supply Current <sup>(4)</sup>	$\Delta I_{CC}$	Per input pin, $V_{CC} = 3.0V$ to 3.6V, one input at $V_{CC} - 0.6V$ , other inputs at $V_{CC}$ or GND	Full		0.2	80	$\mu A$	
Input Capacitance	$C_I$	Input pins, $V_I = 0V$ or 3.0V	+25°C		6		pF	
Output Capacitance	$C_O$	Output pins nQn, outputs disabled, $V_O = 0V$ or $V_{CC}$	+25°C		9		pF	

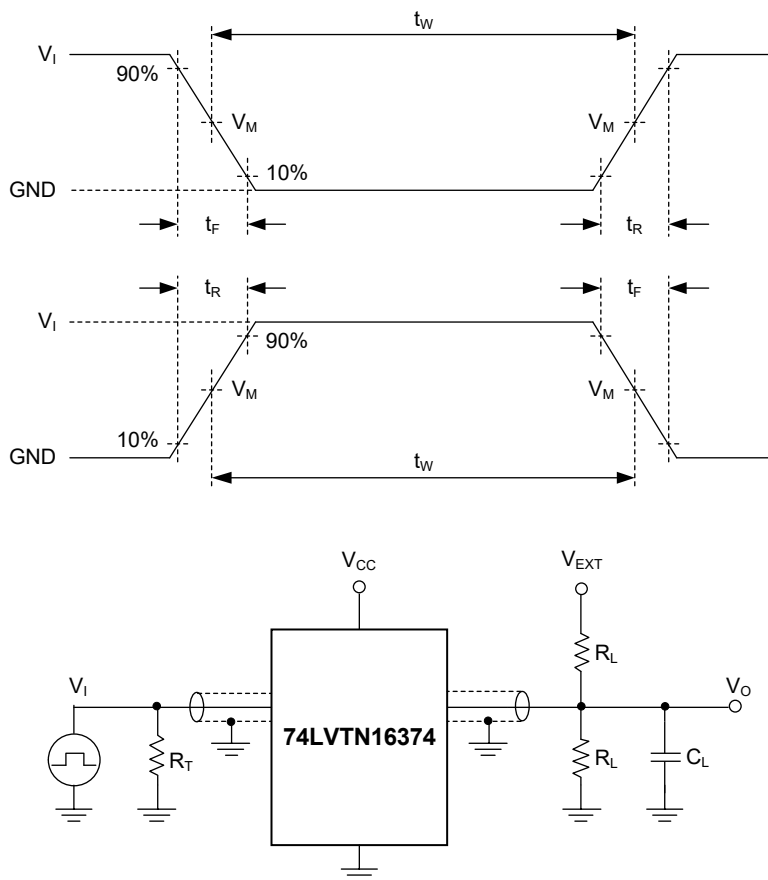
## NOTES:

- For valid test results, data must not be loaded into the flips-flops (or latches) after applying power.
- Unused pins at  $V_{CC}$  or GND.
- $I_{CC}$  is measured with outputs pulled to  $V_{CC}$  or GND.
- This is the increase in supply current for each input at the specified voltage level other than  $V_{CC}$  or GND.

**DYNAMIC CHARACTERISTICS**(For test circuit, see Figure 1. All typical values are measured at  $V_{CC} = 3.3V$  and  $T_A = +25^\circ C$ , unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS
Maximum Frequency	$f_{MAX}$	nCP, $V_{CC} = 3.3V \pm 0.3V$ , see Figure 2	+25°C		150		MHz
Low to High Propagation Delay	$t_{PLH}$	nCP to nQn, see Figure 2	$V_{CC} = 3.3V \pm 0.3V$	+25°C	3.4		ns
			$V_{CC} = 2.7V$	+25°C	3.9		
High to Low Propagation Delay	$t_{PHL}$	nCP to nQn, see Figure 2	$V_{CC} = 3.3V \pm 0.3V$	+25°C	3.3		ns
			$V_{CC} = 2.7V$	+25°C	3.5		
Off-State to High Propagation Delay	$t_{PZH}$	$\overline{nOE}$ to nQn, see Figure 3	$V_{CC} = 3.3V \pm 0.3V$	+25°C	4.3		ns
			$V_{CC} = 2.7V$	+25°C	3.9		
Off-State to Low Propagation Delay	$t_{PZL}$	$\overline{nOE}$ to nQn, see Figure 3	$V_{CC} = 3.3V \pm 0.3V$	+25°C	4.4		ns
			$V_{CC} = 2.7V$	+25°C	4.3		
High to Off-State Propagation Delay	$t_{PHZ}$	$\overline{nOE}$ to nQn, see Figure 3	$V_{CC} = 3.3V \pm 0.3V$	+25°C	4.5		ns
			$V_{CC} = 2.7V$	+25°C	4		
Low to Off-State Propagation Delay	$t_{PLZ}$	$\overline{nOE}$ to nQn, see Figure 3	$V_{CC} = 3.3V \pm 0.3V$	+25°C	3.8		ns
			$V_{CC} = 2.7V$	+25°C	3.4		
Set-Up Time	$t_{SU}$	nDn to nCP, high or low, see Figure 4	$V_{CC} = 3.3V \pm 0.3V$	+25°C	0.3		ns
			$V_{CC} = 2.7V$	+25°C	0.3		
Hold Time	$t_H$	nDn to nCP, high or low, see Figure 4	$V_{CC} = 3.3V \pm 0.3V$	+25°C	0.2		ns
			$V_{CC} = 2.7V$	+25°C	0.2		
Pulse Width	$t_W$	nCP high, see Figure 2	$V_{CC} = 3.3V \pm 0.3V$	+25°C	1.5		ns
			$V_{CC} = 2.7V$	+25°C	1.5		
		nCP low, see Figure 2	$V_{CC} = 3.3V \pm 0.3V$	+25°C	1.5		
			$V_{CC} = 2.7V$	+25°C	1.5		

TEST CIRCUIT



Test conditions are given in Table 1.

Definitions for test circuit:

$R_L$ : Load resistance.

$C_L$ : Load capacitance (includes jig and probe).

$R_T$ : Termination resistance (equals to output impedance  $Z_O$  of the pulse generator).

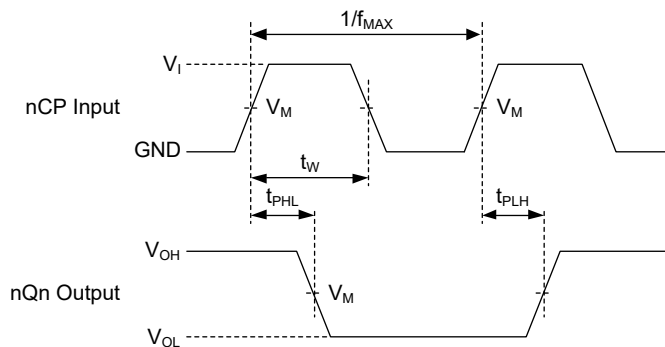
$V_{EXT}$ : External voltage used to measure switching time.

Figure 1. Test Circuit for Measuring Switching Times

Table 1. Test Conditions

SUPPLY VOLTAGE	INPUT				LOAD		$V_{EXT}$		
$V_{CC}$	$V_I$	$f_i$	$t_W$	$t_R, t_F$	$C_L$	$R_L$	$t_{PHZ}, t_{PZH}$	$t_{PLZ}, t_{PZL}$	$t_{PLH}, t_{PHL}$
2.7V to 3.6V	2.7V	$\leq 10\text{MHz}$	500ns	$\leq 2.5\text{ns}$	50pF	500 $\Omega$	GND	6V	Open

WAVEFORMS

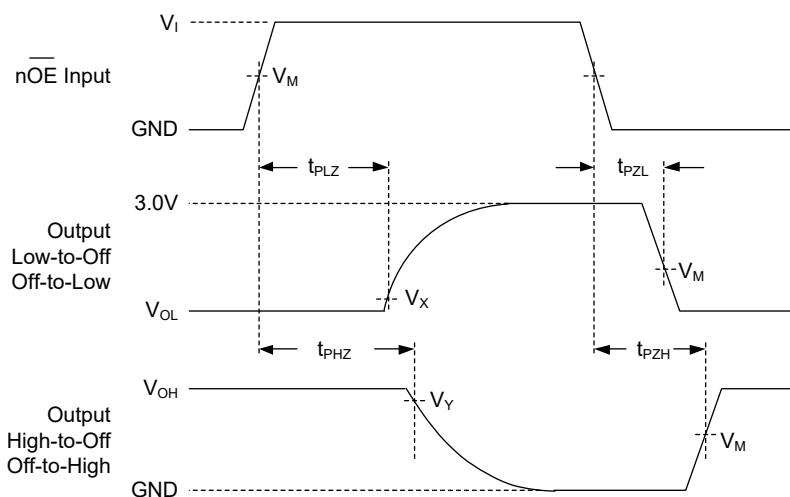


Test conditions are given in Table 1.

Measurement points are given in Table 2.

Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

Figure 2. Clock Input to Output Propagation Delays, Clock Pulse Width and Maximum Clock Frequency



Test conditions are given in Table 1.

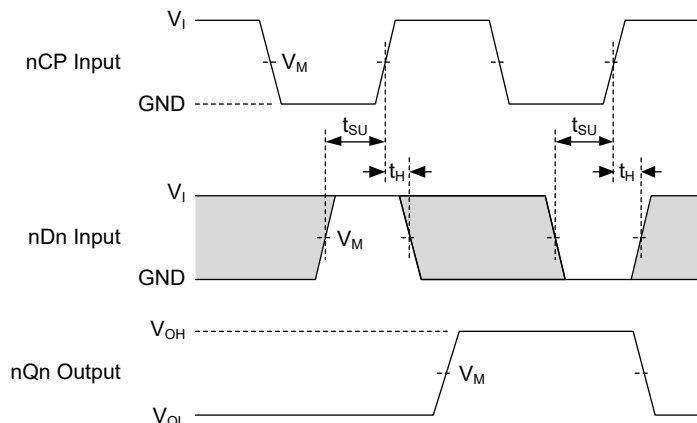
Measurement points are given in Table 2.

Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

Figure 3. Enable and Disable Times



WAVEFORMS (continued)



Test conditions are given in Table 1.

Measurement points are given in Table 2.

Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

The shaded areas indicate when the input is permitted to change for predictable output performance.

Figure 4. Data Set-Up and Hold Times

Table 2. Measurement Points

SUPPLY VOLTAGE	INPUT		OUTPUT		
	$V_I$	$V_M$	$V_M$	$V_X$	$V_Y$
$V_{CC}$ 2.7V to 3.6V	2.7V	1.5V	1.5V	$V_{OL} + 0.3V$	$V_{OH} - 0.3V$

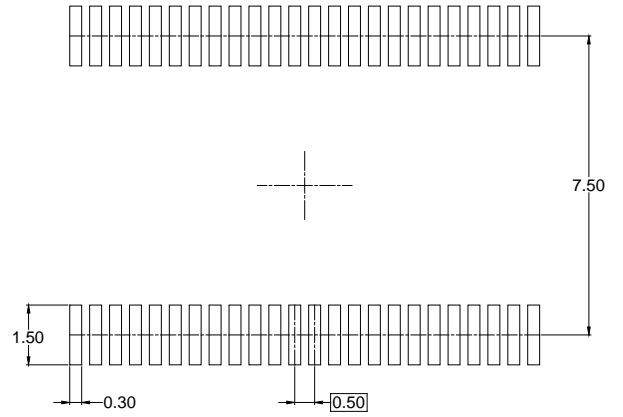
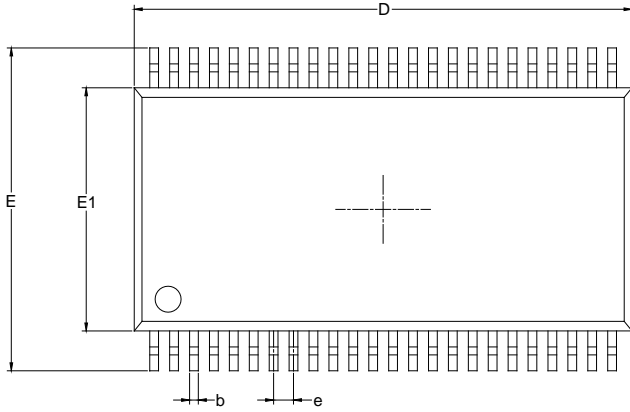
REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

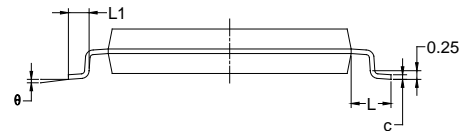
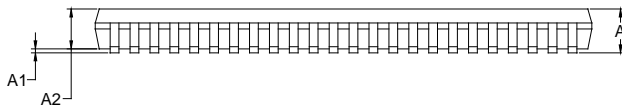
NOVEMBER 2021 – REV.A to REV.A.1	Page
Updated HBM value in Absolute Maximum Ratings section.....	2
Changes from Original (MARCH 2021) to REV.A	Page
Changed from product preview to production data.....	All

PACKAGE OUTLINE DIMENSIONS

TSSOP-48



RECOMMENDED LAND PATTERN (Unit: mm)



Symbol	Dimensions In Millimeters		
	MIN	MOD	MAX
A			1.20
A1	0.05	0.10	0.15
A2	0.85	0.95	1.05
b	0.18		0.26
c	0.15		0.19
D	12.40	12.50	12.60
E	7.90	8.10	8.30
E1	6.00	6.10	6.20
e	0.50 BSC		
L	1.00 REF		
L1	0.45		0.75
$\theta$	0°		8°

NOTES:

1. Body dimensions do not include mode flash or protrusion.
2. This drawing is subject to change without notice.

# PACKAGE INFORMATION

## TAPE AND REEL INFORMATION

### REEL DIMENSIONS



### TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

### KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TSSOP-48	13"	24.4	8.60	13.00	1.80	4.0	12.0	2.0	24.0	Q1

000001

# PACKAGE INFORMATION

## CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

## KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13"	386	280	370	5

DD0002